Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1038	257/776	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:43
L2	77	(semiconductor or die or chip or IC) and (via or hole or open\$3) with semicircle	USPAT	OR	OFF	2005/04/26 21:45
L3	47	(semiconductor or die or chip or IC) and (via or hole or open\$3) with (semicircle or semi-circle) with shape	USPAT	OR	OFF	2005/04/26 21:47
L4	5	(semiconductor or die or chip or IC) same (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle) with shape	USPAT	OR	OFF	2005/04/26 21:47
L5	19	(semiconductor or die or chip or IC) same (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle) with shape	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/26 21:48
L6	215	silicone near oxide with inorganic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:18
L7	29	silicone near oxide with inorganic near material	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:18
L8	243	257/798	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:44
L9	1367	257/303	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:58

L10	2334	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 23:04
L11	1918	228/180.22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 23:04
S1	0	(semiconductor or die or chip or IC) and (via or hole or open\$3) with pad same (via or hole or open\$3) with semicircle	USPAT	OR	OFF	2005/04/26 15:21
S3	87	(semiconductor or die or chip or IC) and (via or hole or open\$3) with semicircle	USPAT; JPO	OR	OFF	2005/04/26 15:30
S4	36875	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape	USPAT; JPO	OR	OFF	2005/04/26 15:31
S5	2	(semiconductor or die or chip or IC) and (via or hole or open\$3) with circule	USPAT; JPO	OR	OFF	2005/04/26 15:31
S6	3605	(semiconductor or die or chip or IC) and (via or hole or open\$3) with circle	USPAT; JPO	OR	OFF	2005/04/26 15:31
S7	75	(semiconductor or die or chip or IC) and (via or hole or open\$3) with semi-circle	USPAT; JPO	OR	OFF	2005/04/26 15:35
S8	3875	(semiconductor or die or chip or IC) and (via or hole or open\$3) with arc	USPAT; JPO	OR	OFF	2005/04/26 15:35
S9	1086	(semiconductor or die or chip or IC) and (via or hole or open\$3) with (pad or electrode or terminal or contact) with arc	USPAT; JPO	OR	ON	2005/04/26 15:35
S10	534	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape with arc	USPAT; JPO	OR	ON	2005/04/26 16:12
S11	219	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape with ellipse	USPAT; JPO	OR	ON	2005/04/26 16:48
S12	47549	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape	USPAT; JPO	OR	ON	2005/04/26 17:37
S13	905	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape with circle	USPAT; JPO	OR	ON	2005/04/26 16:49

S14	1	"4188438".PN.	USPAT;	OR	OFF	2005/04/26 17:27
64.5		#4554275# PM	USOCR	0.0	055	2005/04/25 47 27
S15	1	"4661375".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S16	1	"5084752".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S17	1	"5134460".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S18	1	"5470787".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S19	1	"4686538".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S20	1	"5359351".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S21	1	"5359351".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S22	1	"6037957".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S23	1	"6071427".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S24	1	"6123410".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:29
S25	1	"5939790".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:29
S26	1	"5986343".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:31
S27	1	"6229221".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:31
S28	1	"20010010408".PN.	US-PGPUB	OR	OFF	2005/04/26 17:32
S29	2	"D208222".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:32
S30	2	"0211011".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:32
S31	1	"D263563".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:32
S32 .	1	"3567844".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S33	1	"5513076".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S34	1	"6031283".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S35	1	"6106923".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S36	1	"6166441".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:35

S37	1	"6175158".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:35
S38	1	"6201707".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:36
S39	1	"4609986".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:37
S40	251	S12 and 257/690	USPAT; JPO	OR	ON	2005/04/26 18:16
S41	1152	S12 and (257/774 or 257/776 or 257/798 or 228/180.22 or 257/303 or 257/784)	USPAT; JPO	OR	ON	2005/04/26 19:03
S42	2285	257/690	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 19:30
S43	3401	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 20:41